

ABSTRACT

PROCESSING METHOD FOR WAFER

A processing method for a wafer in which a front surface of the wafer is sealed with a sealing member and a plurality of bumps are formed individually in the chip regions of the sealing member includes an alignment step of picking upon an image of the front surface side of the wafer through the sealing member by visible image pickup means from the front surface side of the wafer to detect alignment marks and detecting a scheduled division line to be laser processed based on the alignment marks, a modified layer formation step of positioning a focus point of a laser beam of a wavelength, which can pass the wafer and the sealing member, in the inside of the wafer or the sealing member and irradiating the laser beam along the scheduled division line from the front surface side of the wafer to form a modified layer in the inside of the wafer and the sealing member, and a division step of applying external force to the wafer and the sealing member to divide the wafer from a division start point given by the modified layer into individual device chips each sealed with the seal member. The alignment step is carried out while light is irradiated in an oblique direction upon a region, whose image is to be picked up by the visible light image pickup means, by oblique light means.

(Figure 4)